EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"US 20070099129"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2008/02/16 10:36
S2	4	jp-07239558-$.did. or jp-06275514-$.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:48
S3	103546	develop$3 with (wafer or substrate)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:51
S4	3389	develop$3 near2 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:52
S5	14388	(wash$3 or rins$3) near2 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:52
S6	3152	(chemical or curing) near2 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55
S7	1016	S3 and S4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55
S8	243	S7 and S5	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55
S9	10	S8 and S6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 10:55

S10	702	(adjuvant or curing) near3 nozzle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:04
S11	28	S3 and S10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:05
S12	73	curing with $5resist with (remain$3 or residual) with develop $4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:12
S13	2	S4 and S12	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:16
S14	6	(355/27.ccls. or 396/611.ccls. or 430/5,30.ccls.) and S12	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:17
S15	7	liquid with curing with $5resist with (remain $3 or residual) with develop$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:21
S16	114	liquid near3 curing with $5resist	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:28
S17	21	S3 and S16	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:28
S18	128995	develop$4 with (wafer or substrate)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:29
S19	25	S16 and S18	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:29

S20	4	curing with $5resist with (remain$3 or residual) with develop $4 same (solvent or liquid or solution) near2 cur$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:36
S21	99	cur$3 with $5resist with develop$4 same (solvent or liquid or solution) near2 cur$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:38
S22	11	cur$3 with $5resist with developed near2 ($5resist or wafer or substrate) same (solvent or liquid or solution) near2 cur$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:46
S23	2786399	(adjuvant or curing) with developed (wafer or substrate)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:52
S24	2522	liquid near3 (adjuvant or curing) same S23	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:52
S25	24	(355/27.ccls. or 396/611.ccls. or 430/5,30.ccls.) and S24	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/16 11:53

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